SS32BF THRU SS320BF

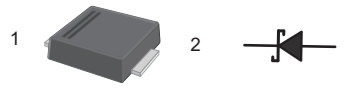
Surface Mount Schottky Barrier Rectifier
Reverse Voltage - 20 to 200V
Forward Current - 3.0A

FEATURES

- Metal silicon junction, majority carrier conduction
- For surface mounted applications
- Low power loss, high efficiency
- High forward surge current capability
- For use in low voltage, high frequency inverters, free wheeling, and polarity protection applications

PINNING

PIN	DESCRIPTION
1	Cathode
2	Anode



Simplified outline SMBF and symbol

MECHANICAL DATA

- Case: SMBF
- Terminals: Solderable per MIL-STD-750, Method 2026
- Approx. Weight: 57mg / 0.002oz

Absolute Maximum Ratings and Electrical characteristics

Ratings at 25 °C ambient temperature unless otherwise specified.Single phase, half wave, 60Hz resistive or inductive load, for capacitive load, derate by 20 %

Parameter	Symbols	SS32BF	SS34BF	SS36BF	SS38BF	SS310BF	SS312BF	SS315BF	SS320BF	Units
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	20	40	60	80	100	120	150	200	V
Maximum RMS voltage	V_{RMS}	14	28	42	56	70	84	105	140	V
Maximum DC Blocking Voltage	V_{DC}	20	40	60	80	100	120	150	200	V
Maximum Average Forward Rectified Current	$I_{F(AV)}$	3.0								A
Peak Forward Surge Current,8.3ms Single Half Sine-wave Superimposed on Rated Load (JEDEC method)	I_{FSM}	80								A
Max Instantaneous Forward Voltage at 3 A	V_F	0.55		0.70		0.85		0.95		V
Maximum DC Reverse Current at Rated DC Reverse Voltage T_a = 25°C T_a =100°C	I_R	0.5 5			0.3 3					mA
Typical Junction Capacitance (1)	C_j	450			400					pF
Typical Thermal Resistance (2)	$R_{\theta JA}$	65								°C/W
Operating Junction Temperature Range	T_j	-55 ~ +125								°C
Storage Temperature Range	T_{stg}	-55 ~ +150								°C

(1) Measured at 1 MHz and applied reverse voltage of 4 V D.C
(2) P.C.B. mounted with 2.0" X 2.0" (5 X 5 cm) copper pad areas.

Fig.1 Forward Current Derating Curve

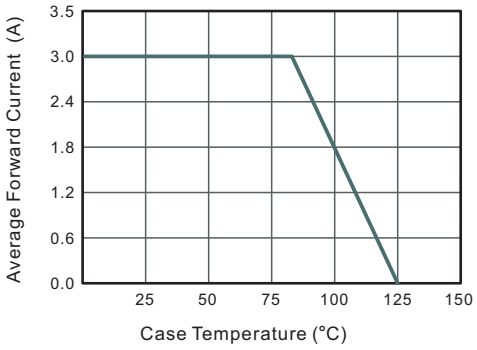


Fig.2 Typical Reverse Characteristics

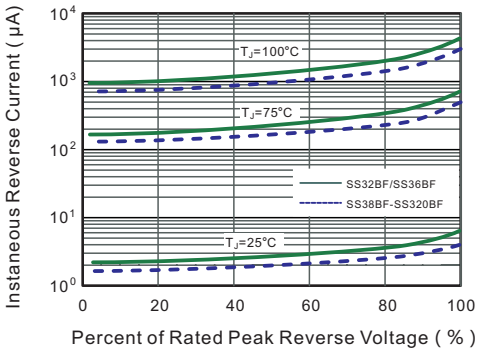


Fig.3 Typical Forward Characteristic

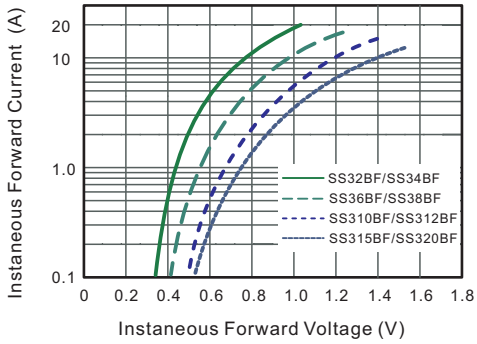


Fig.4 Typical Junction Capacitance

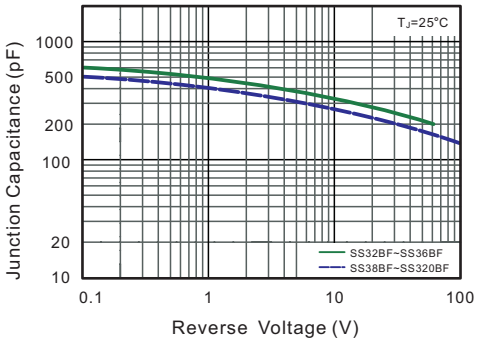


Fig.5 Maximum Non-Repetitive Peak Forward Surage Current

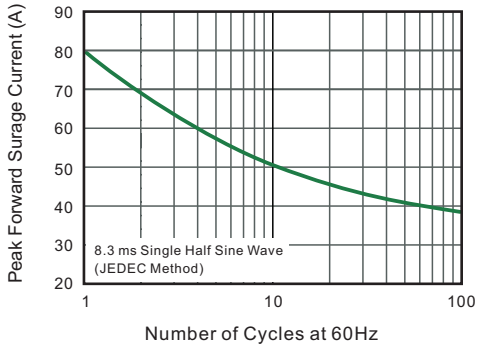
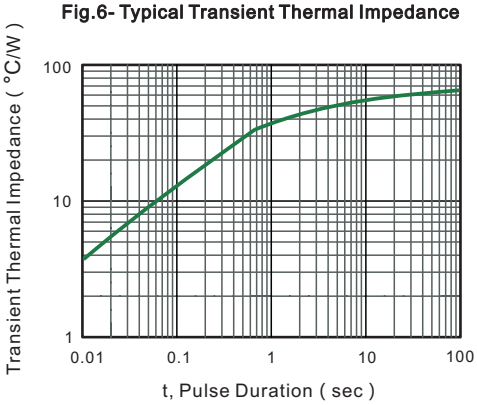


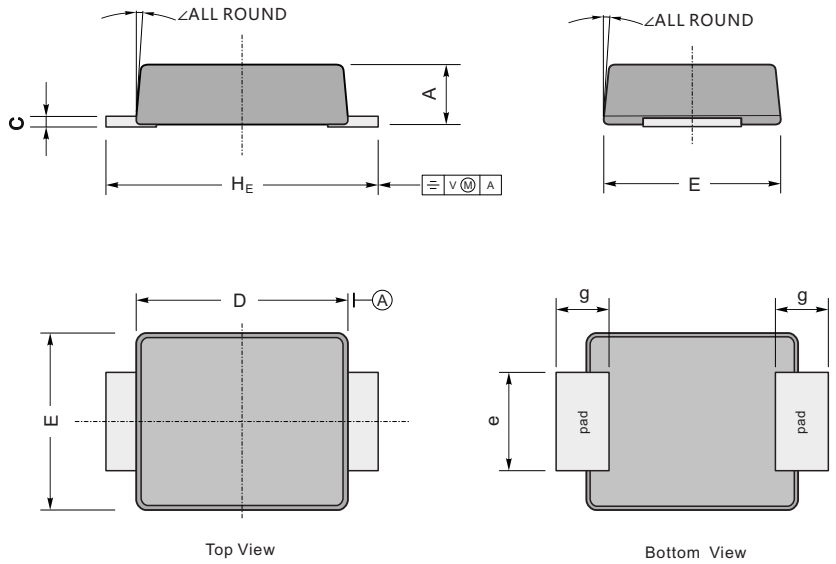
Fig.6- Typical Transient Thermal Impedance

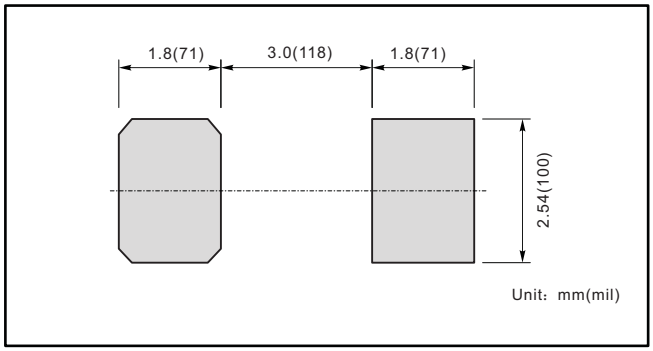


PACKAGE OUTLINE

Plastic surface mounted package; 2 leads

SMBF



UNIT		A	C	D	E	H_E	e	g	∠
mm	max	1.3	0.26	4.4	3.7	5.5	2.2	1.0	9°
	min	1.1	0.18	4.2	3.5	5.1	1.9		
mil	max	51	10	173	146	216	86	40	
	min	43	7	165	138	200	75		

The recommended mounting pad size